Abstracts

A Novel Concept for mm-Wave MMIC Interconnects and Packaging

G. Strauss and W. Menzel. "A Novel Concept for mm-Wave MMIC Interconnects and Packaging." 1994 MTT-S International Microwave Symposium Digest 94.2 (1994 Vol. II [MWSYM]): 1141-1144.

Standard intercomect and packaging techniques for MMICs tend to get more and more difficult at mm-wave frequencies due to the increased influence of discontinuities and tolerances, especially in conjunction with temperature and hermetic sealing. To overcome these problems, a novel concept is proposed based on electromagnetic field coupling for interconnects and package feed-through elements. First theoretical and (scaled) experimental results are presented.

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